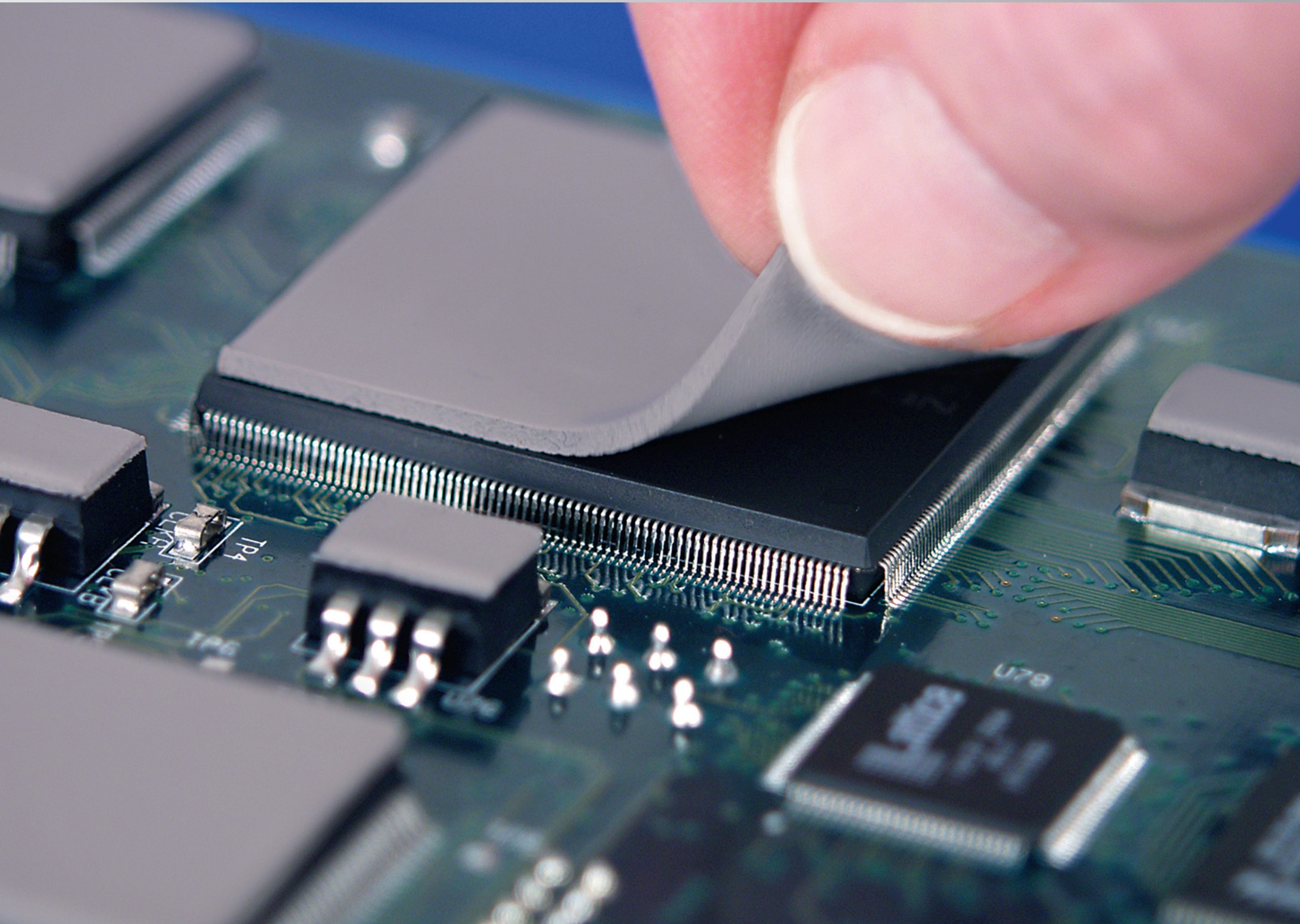
BERGQUIST®



BERGQUIST® GAP PAD® TGP 7000ULM

ULTRA-LOW MODULUS, HIGH THERMAL CONDUCTIVITY GAP FILLING MATERIAL

BERGQUIST® GAP PAD® TGP 7000ULM is a high thermal conductivity, ultra-low modulus thermal interface material designed for modern telecom and datacom applications where high power densities are the norm. The soft, conforming characteristics of BERGQUIST® GAP PAD® TGP 7000ULM ensure excellent wet out at the interface even on rough or irregular surfaces, delivering optimized thermal transfer and minimizing assembly stress. A silicone-based resin platform and unique filler technology enable high, 7.0 W/m-K thermal conductivity while prioritizing stress reduction on miniaturized, delicate components. BERGQUIST® GAP PAD® TGP 7000ULM is supplied in easy-to-use pre-cut pads and has an inherent high tack on both sides.

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Key Benefits

- Low assembly stress due to ultra-low modulus (Shore 000, ASTM D2240)
- Excellent conformability to rough or irregular surfaces
- Thorough wet out at the interface for maximized thermal transfer
- High thermal conductivity of 7.0 W/m-K
- Simplified application and processability; supplied in pre-cut, custom-sized pads with high tack on both sides
- Room-temperature storage

PROPERTIES		BERGQUIST® GAP PAD® TGP 7000ULM
Physical Properties	Young's Modulus (kPa)	152
	Appearance	Gray
Thermal Properties	Thermal Conductivity (W/m•K)	7.0
Electrical Properties	Dielectric Breakdown Voltage (40 mil, VAC)	> 5,000
	Volume Resistivity (Ω•m)	1.2×10^{11}
Safety Testing	Flammability Rating	UL 94 V-0

Typical applications

- **Telecommunications** (routers, switches and base stations)
- Optical Transceivers
- ASICs and DSPs

Across the Board, Around the Globe.

henkel-adhesives.com/thermal

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